### SN74ALVCH16841 20-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

SCES043E-JULY 1995-REVISED SEPTEMBER 2004

### **FEATURES**

- Member of the Texas Instruments Widebus™
   Family
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

#### DESCRIPTION

This 20-bit bus-interface D-type latch is designed for 1.65-V to 3.6-V  $V_{\rm CC}$  operation.

The SN74ALVCH16841 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, unidirectional bus drivers, and working registers.

The SN74ALVCH16841 can be used as two 10-bit latches or one 20-bit latch. The 20 latches are transparent D-type latches. The device has noninverting data (D) inputs and provides true data at its outputs. While the latch-enable (1LE or 2LE) input is high, the Q outputs of the corresponding 10-bit latch follow the D inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

## DGG OR DL PACKAGE (TOP VIEW)

1 <del>0E</del>		1	$\cup$	56		1LE
1Q1	D	2		55	1	1D1
1Q2		3		54		1D2
GND		4		53		GND
1Q3		5		52		1D3
1Q4		6		51		1D4
$V_{CC}$		7		50		$V_{CC}$
1Q5		8		49	1	1D5
1Q6		9		48	0	1D6
1Q7		10		47		1D7
GND		11		46	0	GND
1Q8		12		45		1D8
1Q9		13		44	р	1D9
1Q10		14		43		1D10
2Q1		15		42		2D1
2Q2		16		41		2D2
2Q3		17		40		2D3
GND		18		39		GND
2Q4		19		38		2D4
2Q5		20		37	1	2D5
2Q6		21		36		2D6
$V_{CC}$		22		35		$V_{CC}$
2Q7		23		34	•	2D7
2Q8		24		33		2D8
GND		25		32		GND
2Q9		26		31		2D9
2Q10	ď	27		30		2D10
2 <del>OE</del>	q	28		29		2LE
					•	

A buffered output-enable ( $1\overline{OE}$  or  $2\overline{OE}$ ) input can be used to place the outputs of the corresponding 10-bit latch in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly.

 $\overline{\text{OE}}$  does not affect the internal operation of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16841 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

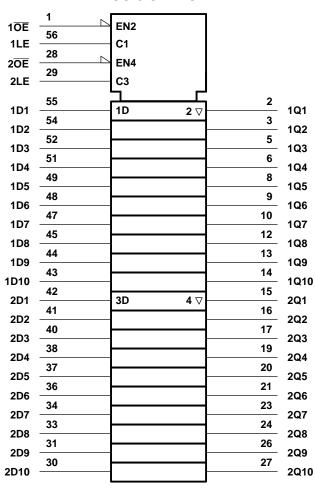
Widebus, EPIC are trademarks of Texas Instruments.



## FUNCTION TABLE (each 10-bit latch)

	INPUTS		OUTPUT
ŌĒ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	$Q_0$
Н	X	X	Z

### LOGIC SYMBOL(1)

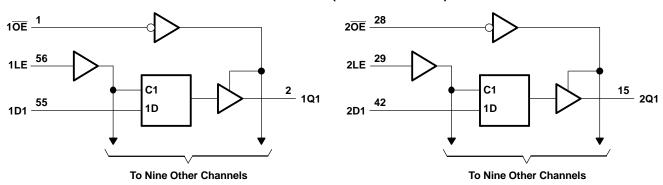


<sup>&</sup>lt;sup>(1)</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.





### **LOGIC DIAGRAM (POSITIVE LOGIC)**



### ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
$V_{CC}$	Supply voltage range			-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>			-0.5	4.6	V
Vo	Output voltage range <sup>(2)(3)</sup>			-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0			-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50		mA
Io	Continuous output current				±50	mA
	Continuous current through each V <sub>CC</sub> or GN	D			±100	mA
0	Dealer at the world in a dealer (4)	DGG package			81	0000
$\theta_{JA}$	Package thermal impedance (4)	DL package 74		°C/W		
T <sub>stg</sub>	Storage temperature range			-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> This value is limited to 4.6 V maximum.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51.

## SN74ALVCH16841 20-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS





### **RECOMMENDED OPERATING CONDITIONS**(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		8.0	
V <sub>I</sub>	Input voltage		0	V <sub>CC</sub>	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4	
	High level output ourrent	$V_{CC} = 2.3 \text{ V}$		-12	A
I <sub>OH</sub>	High-level output current	$V_{CC} = 2.7 V$		-12	mA
		$V_{CC} = 3 V$		-24	
		V <sub>CC</sub> = 1.65 V		4	
	Low-level output current	$V_{CC} = 2.3 \text{ V}$		12	m Λ
I <sub>OL</sub>	Low-level output current	$V_{CC} = 2.7 V$		12	mA
		$V_{CC} = 3 V$		24	
Δt/Δν	Input transition rise or fall rate	·		10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

<sup>(1)</sup> All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SCES043E-JULY 1995-REVISED SEPTEMBER 2004

### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN TYP(1) MAX	UNIT					
	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2						
	I <sub>OH</sub> = -4 mA	1.65 V	1.2						
	I <sub>OH</sub> = -6 mA	2.3 V	2						
$V_{OH}$		2.3 V	1.7	V					
	I <sub>OH</sub> = -12 mA	2.7 V	2.2						
		3 V	2.4						
	I <sub>OH</sub> = -24 mA	3 V	2						
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2						
	I <sub>OL</sub> = 4 mA	1.65 V	0.45						
W	I <sub>OL</sub> = 6 mA	2.3 V	0.4						
$V_{OL}$	10	2.3 V	0.7	V					
	I <sub>OL</sub> = 12 mA	2.7 V	0.4						
	I <sub>OL</sub> = 24 mA	3 V	0.55						
I <sub>I</sub>	$V_I = V_{CC}$ or GND	3.6 V	±5	μΑ					
	V <sub>I</sub> = 0.58 V	1.65 V	25						
	V <sub>I</sub> = 1.07 V	1.65 V	-25						
	V <sub>I</sub> = 0.7 V	2.3 V	45						
I <sub>I(hold)</sub>	V <sub>I</sub> = 1.7 V	2.3 V	-45	μΑ					
, ,	V <sub>I</sub> = 0.8 V	3 V	75						
	V <sub>I</sub> = 2 V	3 V	-75						
	$V_1 = 0 \text{ to } 3.6 \text{ V}^{(2)}$	3.6 V	±500						
l <sub>oz</sub>	$V_O = V_{CC}$ or GND	3.6 V	±10	μΑ					
I <sub>CC</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	40	μΑ					
$\Delta I_{CC}$	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750	μΑ					
Control inputs		0.01/	4.5	pF					
C <sub>i</sub> Data inputs	$V_{I} = V_{CC}$ or GND	3.3 V	6.5						
C <sub>o</sub> Outputs	$V_O = V_{CC}$ or GND	3.3 V	7	pF					

### **TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		$V_{CC}$ = 3.3 V $\pm$ 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration, LE high or low	(1)		3.3		3.3		3.3		ns
$t_{su}$	Setup time, data before LE↑	(1)		0.9		0.7		1.1		ns
t <sub>h</sub>	Hold time, data after LE↑	(1)		1.2		1.5		1.1		ns

<sup>(1)</sup> This information was not available at the time of publication.

All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

## SN74ALVCH16841 20-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

SCES043E-JULY 1995-REVISED SEPTEMBER 2004



### **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V	$V_{CC}$ = 2.5 V $\pm$ 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(001701)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	AX
4	D	Q	(1)	1	5		4.7	1.2	3.9	20
<sup>L</sup> pd	LE	Q	(1)	1	5.6		5.1	1	4.3	ns
t <sub>en</sub>	ŌĒ	Q	(1)	1	6.2		6	1	4.9	ns
t <sub>dis</sub>	ŌĒ	Q	(1)	1.1	5.3		4.3	1.3	4.1	ns

<sup>(1)</sup> This information was not available at the time of publication.

### **OPERATING CHARACTERISTICS**

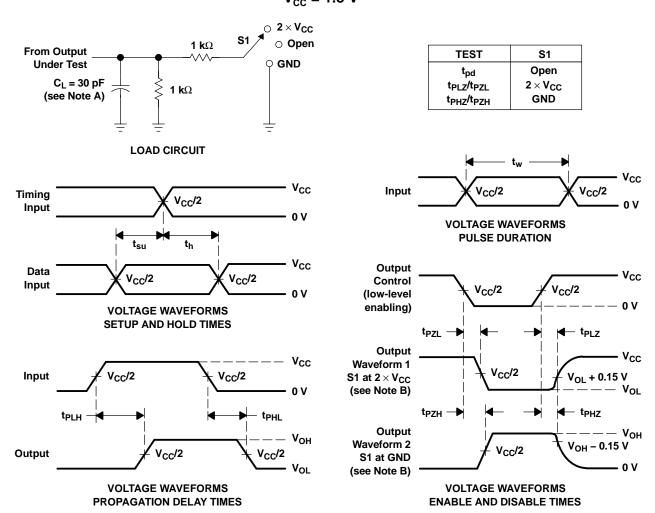
 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
<u> </u>	Power dissipation Outputs enabled		C 50 pF f 10 MHz	(1)	12	20	, C
C <sub>pd</sub>	capacitance	Outputs disabled	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	(1)	1	3	pF

<sup>(1)</sup> This information was not available at the time of publication.



# PARAMETER MEASUREMENT INFORMATION $V_{cc} = 1.8 \text{ V}$



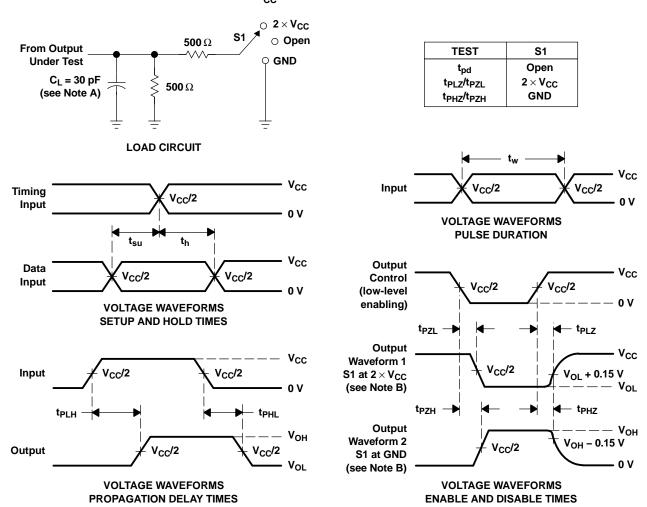
NOTES: A. C<sub>1</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>Pl 7</sub> and t<sub>PH7</sub> are the same as t<sub>dis</sub>.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 1. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.5 V $\pm$ 0.2 V



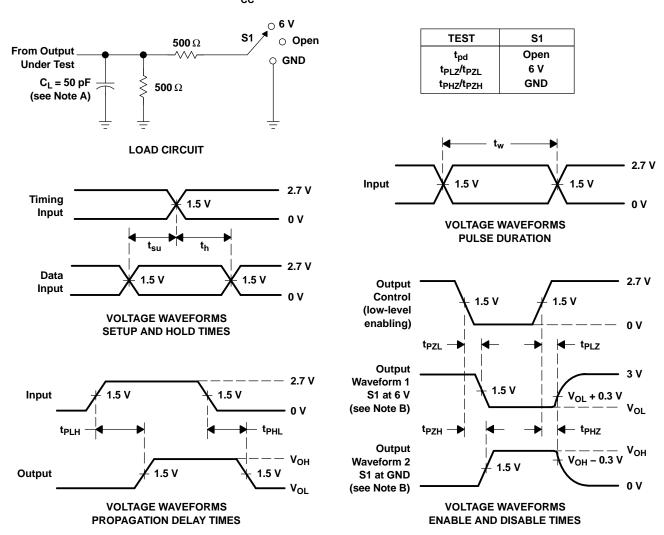
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F.  $t_{PZI}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 2. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms

www.ti.com 17-Jun-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(6)
74ALVCH16841DGGRG4	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
74ALVCH16841DGGRG4.B	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
SN74ALVCH16841DGGR	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
SN74ALVCH16841DGGR.B	Active	Production	TSSOP (DGG)   56	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
SN74ALVCH16841DL	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
SN74ALVCH16841DL.B	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
SN74ALVCH16841DLR	Active	Production	SSOP (DL)   56	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841
SN74ALVCH16841DLR.B	Active	Production	SSOP (DL)   56	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16841

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## **PACKAGE OPTION ADDENDUM**

www.ti.com 17-Jun-2025

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCH16841DGGRG4	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1
SN74ALVCH16841DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1
SN74ALVCH16841DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 24-Jul-2025



### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVCH16841DGGRG4	TSSOP	DGG	56	2000	356.0	356.0	45.0
SN74ALVCH16841DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0
SN74ALVCH16841DLR	SSOP	DL	56	1000	356.0	356.0	53.0

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 24-Jul-2025

### **TUBE**



### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALVCH16841DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ALVCH16841DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

## DL (R-PDSO-G56)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025. Texas Instruments Incorporated